

NICOLAS REED

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EDUCATION

University of California, Berkeley

B.S. Electrical Engineering & Computer Sciences (EECS)

GPA: 3.66/4.00

Expected May 2027

Relevant coursework: Tapeout, Digital Design and Integrated Circuits (with ASIC Lab), Computer Architecture, Operating Systems, Signals and Circuits, Data Structures, Internet of Things, Foundations of Data Science

EXPERIENCE

Apple

[Incoming] Hardware Engineering Intern

Cupertino, CA

May 2026 – August 2026

- Silicon Engineering Group: SoC Design Verification

Sandisk

Software Development Intern

Milpitas, CA

May 2025 – August 2025

- Reconciled CMDB and inventory data for 40,000+ virtual machines with Pandas, standardizing records, surfacing gaps, and producing migration plans for a cloud provider transition.
- Built an AI assistant with LlamaIndex and NLP to streamline license and contract workflows across 10,000 enterprise applications, improving compliance and reducing spend.

UC Berkeley SLICE Lab

Undergraduate Research Assistant - advised by Professor Sagar Karandikar

Berkeley, CA

May 2025 – Present

- Created a telemetry pipeline for Chipyard and FireSim on AWS S3, boosting debugging and reproducibility.
- Prepared a structured dataset of runs and metrics to enable LLM-driven regression triage and automated insights.

UC Berkeley Electrical Engineering & Computer Sciences (EECS)

Head Teaching Assistant

Berkeley, CA

June 2024 – Present

- Support 1,200+ students with C, RISC-V, and Python through office hours and an online forum.
- Ranked 1st among staff in helpfulness and teaching effectiveness.
- Host weekly lab sections for 50+ students, guiding programming exercises and problem-solving practice.
- Develop weekly homework and lab assignments, and maintain course infrastructure using GitHub and Docker.
- Answer 1,500+ student questions per semester to lead online forum engagement.

Micross Components - Silicon Turnkey Solutions

Engineering Intern

Milpitas, CA

July 2023 – August 2023

- Conducted mechanical and PCB testing on 1,000+ devices, translating results into actionable insights via Excel.
- Resolved a test issue by documenting compromised semiconductors and identifying the damage stage.

PROJECTS

TSMC 16nm IoT SoC Tapeout - *Chisel, Chipyard, Hammer*

2026

- Contributed to a large-scale SoC tapeout with Apple mentorship, owning a block and driving signoff closure.

5-Stage Pipelined RISC-V CPU with I/D Caches - *Verilog*

2025

- Apple New Silicon Initiative Design Contest Winner: delivered best performance and area.
- Boosted throughput and frequency by refining hazard control and forwarding, reducing stall cycles.
- Achieved single-cycle read hits and two-cycle write hits and implemented optimized write-back logic.

Pintos Operating System - *C*

2025

- Extended core OS support for process control and system calls, handling invalid user memory safely.
- Added multithreading and synchronization primitives, enforcing priority scheduling to prevent inversion.
- Built UNIX-style file system features including caching, file growth, and subdirectories to improve I/O.

Scheme Interpreter - *Python*

2024

- Implemented an interpreter for a subset of Lisp (Scheme), supporting core expressions and syntax.
- Applied semantic and lexical analysis techniques that machines use to evaluate and execute code.

TECHNICAL SKILLS

Languages: Verilog, SystemVerilog, C, Python, RISC-V, Chisel, Scala, Java, x86. SQL, MATLAB

Tools & Frameworks: Git, Cadence Innovus, GDB, Valgrind, Pandas, NumPy, Docker, LTSpice